



# **PRODUCT DATASHEET**



- PTH Housing Lamp
- Green 570nm

Release Date: 31 October 2024 Version: A1.1

# N0G09H21SV

Housing Lamp



# **Housing Lamp**



# **FEATURES:**

- Package: PTH Housing Lamp 1x 3mm Round
- Forward Current: 20mA\*
- Forward Voltage (typ.): 2.1V
- Luminous Intensity (typ.): 35mcd@20mA
- Colour: Green
- Dominant Wavelength (typ.): 570nm
- Viewing Angle: 50° .
- Materials:
  - Die: AlInGaP \_
  - Resin: Epoxy (Green Diffused) \_
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping Parameters:** .
  - Forward voltage \_
  - Luminous intensity
  - Dominant wavelength
- Soldering Methods: Hand; Soldering Heat (DIP)
- Packing: bulk in bag

**Control System** 

**APPLICATIONS:** 

Indicator

Server

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# CHARACTERISTICS:

## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	lf	25*	mA
Peak Forward Current Duty 1/10@10KHz	IFP	100	mA
Reverse Voltage	V <sub>R</sub>	5	V
Reverse Current @5V	IR	10	μΑ
Power Dissipation	PD	85	mW
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

## Electrical & Optical Characteristics (Ta=25°C)

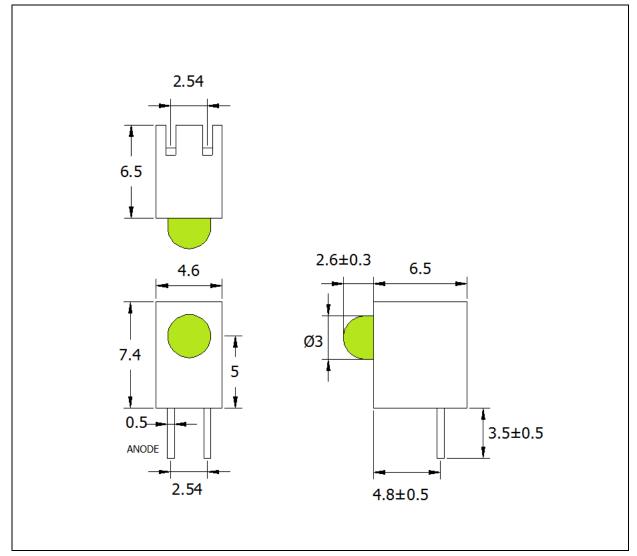
Darameter	Symbol	Values			Unit	Test
Parameter		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	$V_{\text{F}}$	1.8	2.1	2.4	V	I⊧=20mA
Luminous Intensity	lv	25	35	50	mcd	I⊧=20mA
Dominant Wavelength	$\lambda_{D}$	567	570	573	nm	I⊧=20mA
Peak Wavelength	$\lambda_{P}$		570		nm	I⊧=20mA
Spectral Line Half Bandwidth	Δλ		30		nm	I⊧=20mA
Viewing Angle	20 <sub>1/2</sub>		50		deg	I <sub>F</sub> =20mA

1. Luminous intensity (I<sub>v</sub>) ±15%, Forward Voltage (V<sub>F</sub>) ±0.1V, Viewing angle( $2\theta_{1/2}$ ) ±5%



## **OUTLINE DIMENSION:**

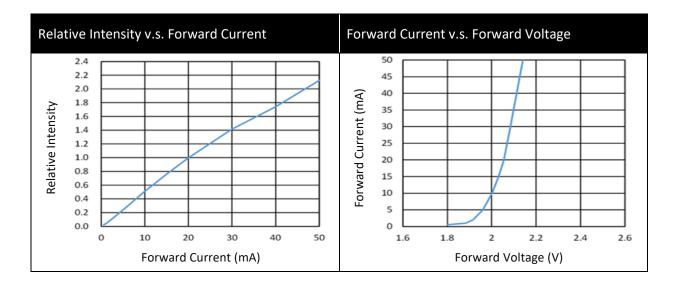
### Package Dimension:

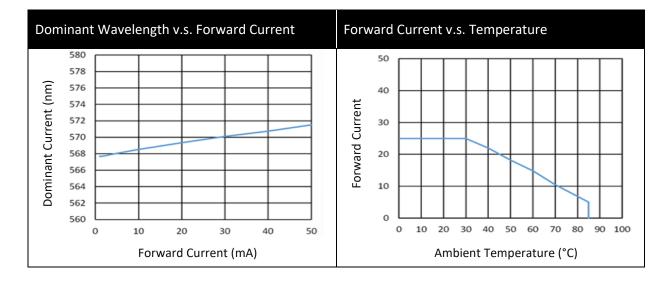


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



# **ELECTRO-OPTICAL CHARACTERISTICS:**





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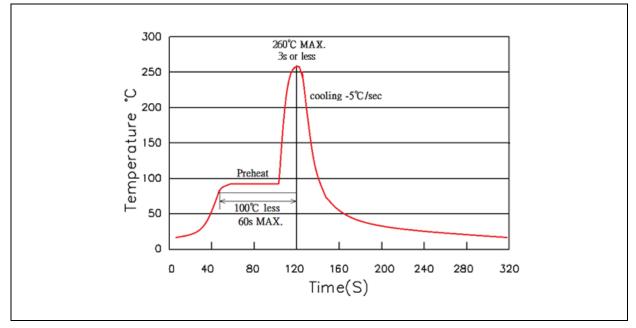


## **RECOMMENDED SOLDERING PROFILE:**

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max. (25W Max.).
- Soldering Time: 3 seconds ± 1 sec.

### Soldering Heat (DIP):



Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.

## **PRECAUTIONS OF USE:**



### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

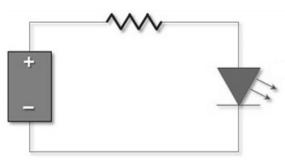
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

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# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	20/06/2023	Datasheet set-up.
A1.1	31/10/2024	Update intensity level.